



# PESD5V0X1UAB

Ultra low capacitance unidirectional ESD protection diode

Rev. 1 — 15 February 2011

Product data sheet

## 1. Product profile

### 1.1 General description

Ultra low capacitance unidirectional ElectroStatic Discharge (ESD) protection diode in a SOD523 (SC-79) ultra small and flat lead Surface-Mounted Device (SMD) plastic package designed to protect one signal line from the damage caused by ESD and other transients.

The combination of extremely low capacitance and ultra low clamping voltage makes the device ideal for high-speed data line protection applications.

### 1.2 Features and benefits

- ESD protection of one line
- Ultra low diode capacitance  
 $C_d = 1.55 \text{ pF}$
- Ultra low clamping voltage:  $V_{CL} = 9 \text{ V}$
- Ultra low leakage current:  $I_{RM} = 1 \text{ nA}$
- ESD protection up to 15 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge);  $I_{PP} = 2 \text{ A}$
- AEC-Q101 qualified

### 1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- 10/100/1000 Mbit/s Ethernet
- Communication systems
- Portable electronics
- Subscriber Identity Module (SIM) card protection
- USB, High-Definition Multimedia Interface (HDMI), FireWire
- High-speed data lines

### 1.4 Quick reference data

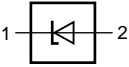

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RWM}$	reverse standoff voltage		-	-	5.5	V
$C_d$	diode capacitance	$f = 1 \text{ MHz}; V_R = 0 \text{ V}$	-	1.55	1.75	pF



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	
2	anode		006aaa152

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PESD5V0X1UAB	SC-79	plastic surface-mounted package; 2 leads	SOD523

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PESD5V0X1UAB	Y2

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$I_{PP}$	peak pulse current	$t_p = 8/20 \mu s$	[1][2]	2	A
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-55	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Non-repetitive current pulse 8/20  $\mu s$  exponential decay waveform according to IEC 61000-4-5.

[2] Measured from pin 1 to 2.

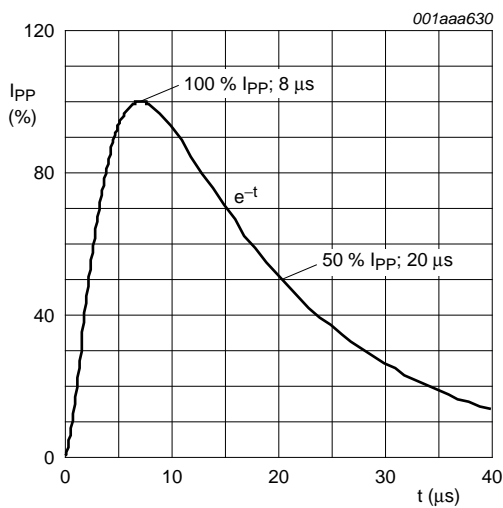
**Table 6. ESD maximum ratings**  
*T<sub>amb</sub> = 25 °C unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>ESD</sub>	electrostatic discharge voltage	IEC 61000-4-2 (contact discharge)	[1][2] -	15	kV
		machine model	-	2000	V
		MIL-STD-883 (human body model)	[2] -	10	kV

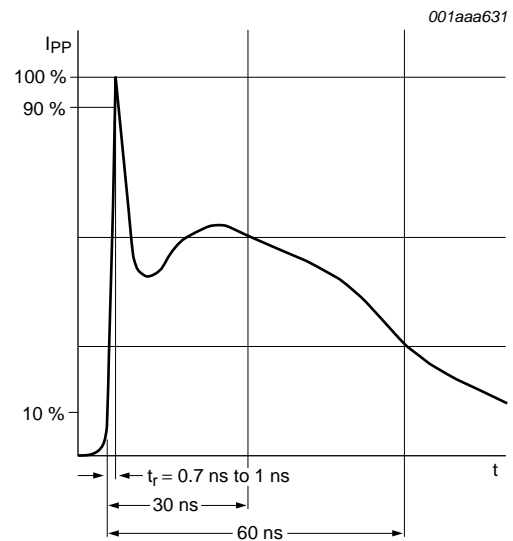
- [1] Device stressed with ten non-repetitive ESD pulses.
- [2] Measured from pin 1 to 2.

**Table 7. ESD standards compliance**

Standard	Conditions
IEC 61000-4-2; level 4 (ESD)	> 15 kV (air); > 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 4 kV



**Fig 1. 8/20 μs pulse waveform according to IEC 61000-4-5**



**Fig 2. ESD pulse waveform according to IEC 61000-4-2**

## 6. Characteristics

**Table 8. Characteristics**

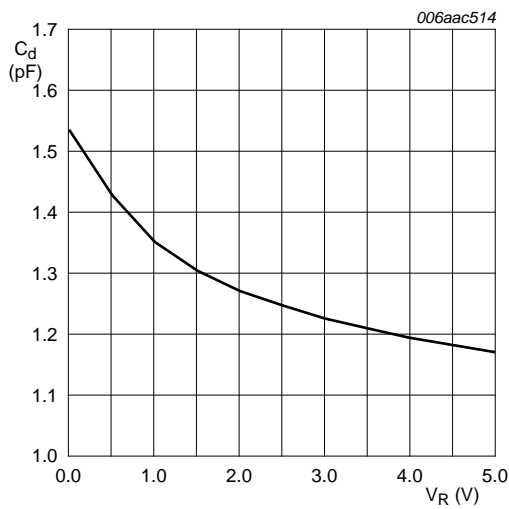
$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RWM}$	reverse standoff voltage		-	-	5.5	V
$I_{RM}$	reverse leakage current	$V_{RWM} = 5\text{ V}$	-	1	100	nA
$V_{BR}$	breakdown voltage	$I_R = 10\text{ mA}$	5.8	7.5	10	V
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$	-	1.55	1.75	pF
$V_{CL}$	clamping voltage	$I_{PP} = 2\text{ A}$	[1][2]	9	-	V
$r_{dyn}$	dynamic resistance	$I_R = 10\text{ A}$	[3]	0.15	-	$\Omega$

[1] Non-repetitive current pulse 8/20  $\mu\text{s}$  exponential decay waveform according to IEC 61000-4-5.

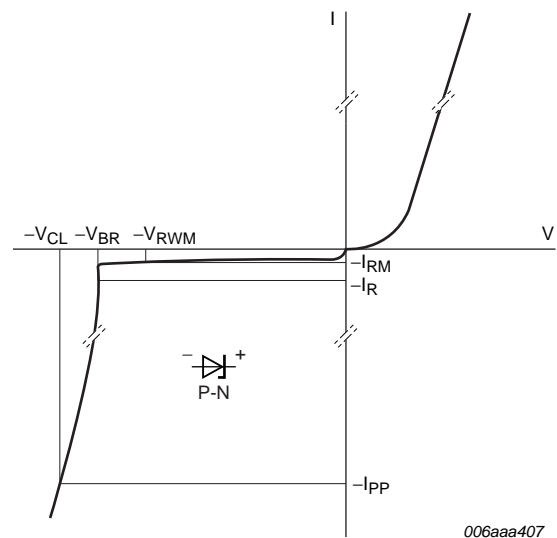
[2] Measured from pin 1 to 2.

[3] Non-repetitive current pulse, Transmission Line Pulse (TLP)  $t_p = 100\text{ ns}$ ; square pulse; ANS/IESD STM5-1-2008.



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig 3. Diode capacitance as a function of reverse voltage; typical values**



**Fig 4. V-I characteristics for a unidirectional ESD protection diode**

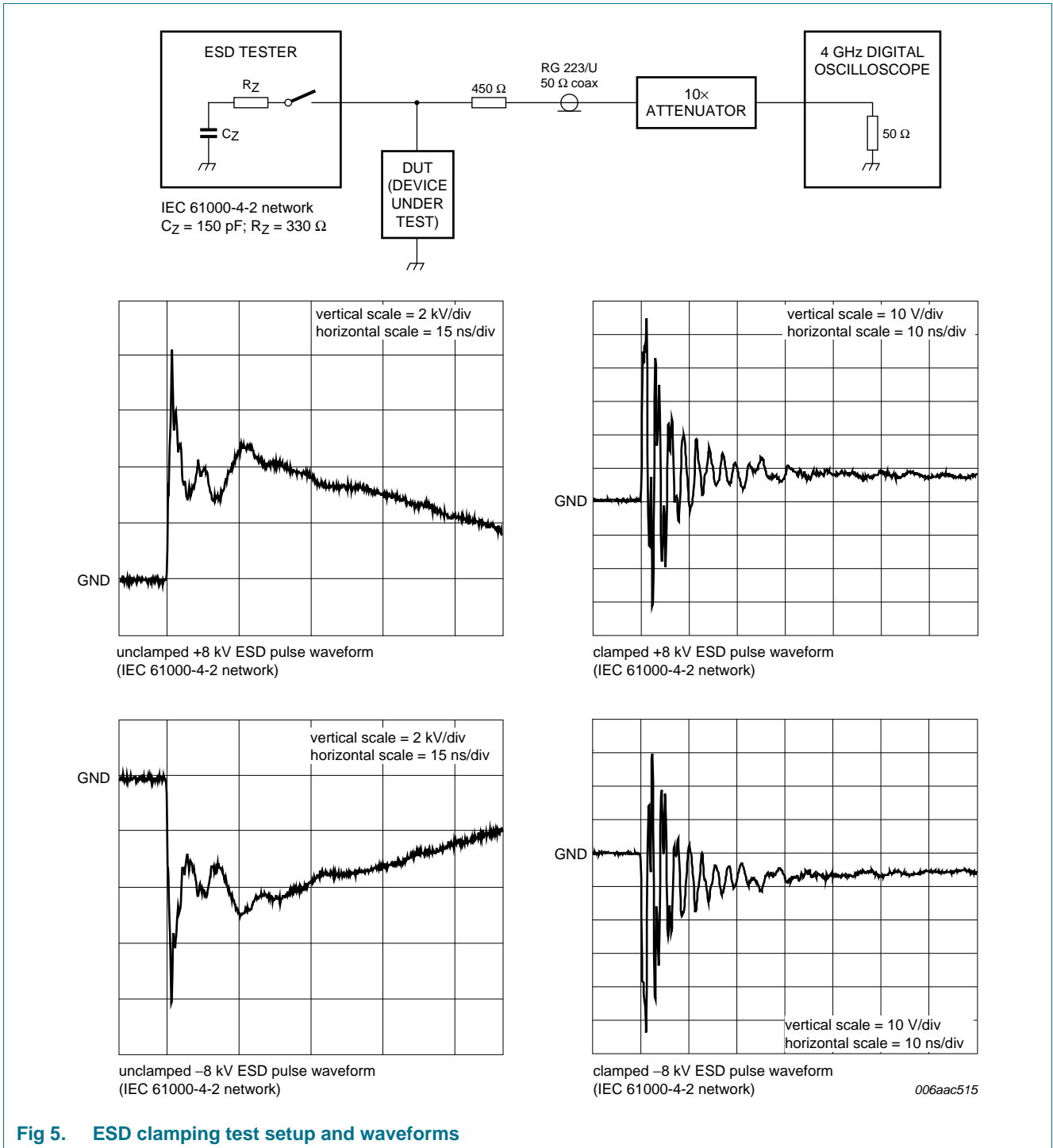
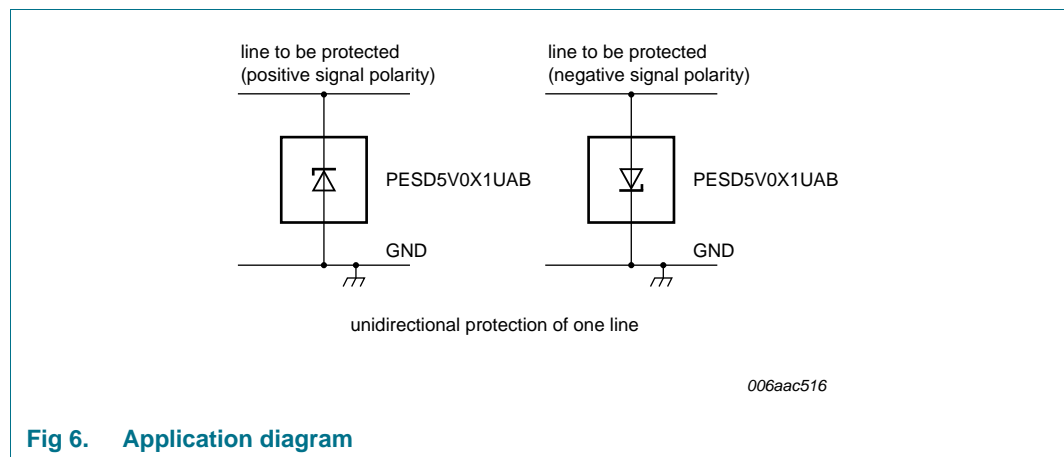


Fig 5. ESD clamping test setup and waveforms

## 7. Application information

The PESD5V0X1UAB is designed for the protection of one unidirectional data or signal line from the damage caused by ESD and surge pulses. The device may be used on lines where the signal polarities are either positive or negative with respect to ground.



**Fig 6. Application diagram**

### Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

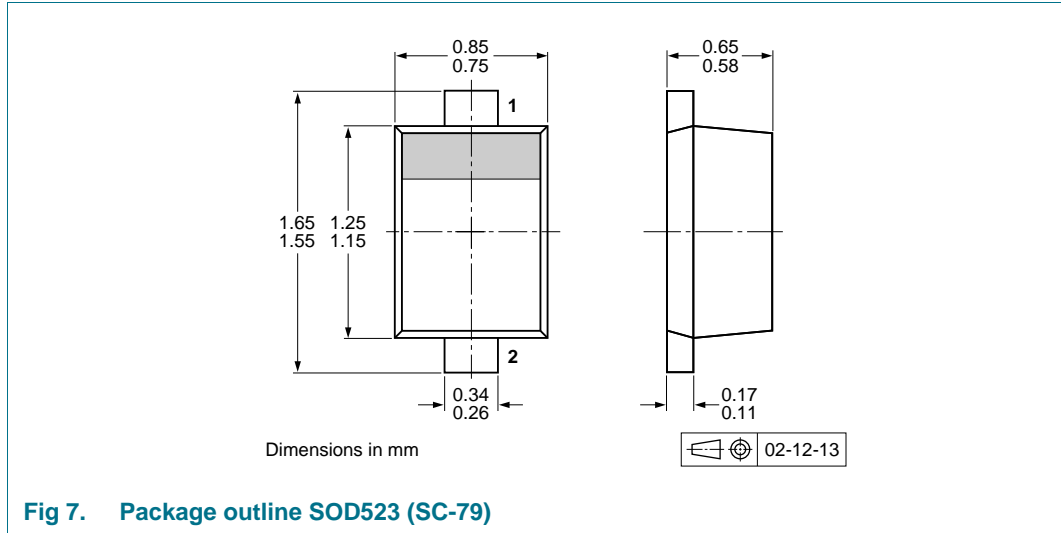
1. Place the PESD5V0X1UAB as close to the input terminal or connector as possible.
2. The path length between the PESD5V0X1UAB and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



**Fig 7. Package outline SOD523 (SC-79)**

**10. Packing information**

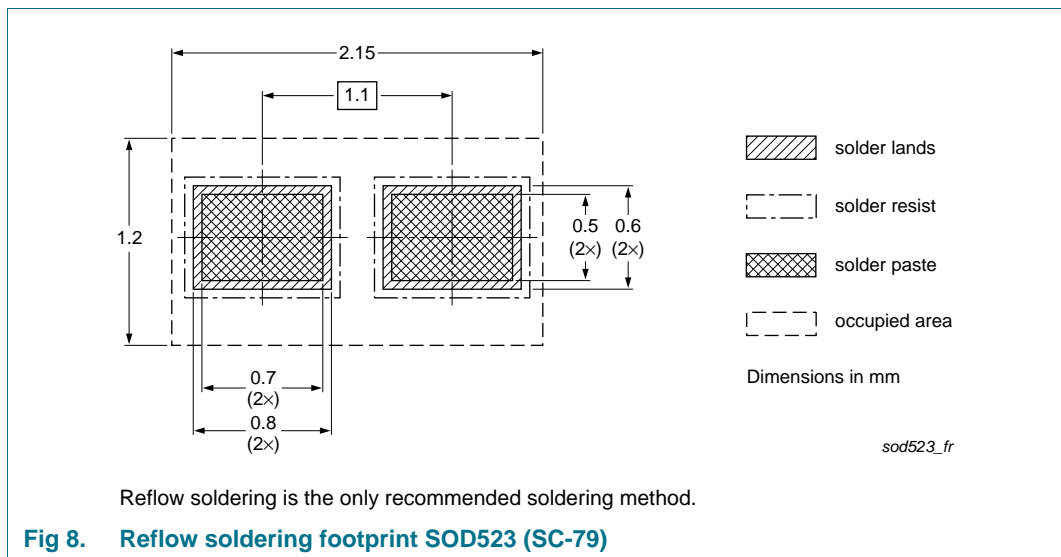
**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity		
			3000	8000	10000
PESD5V0X1UAB	SOD523	2 mm pitch, 8 mm tape and reel	-	-315	-
		4 mm pitch, 8 mm tape and reel	-115	-	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**



**Fig 8. Reflow soldering footprint SOD523 (SC-79)**

## 12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESD5V0X1UAB v.1	20110215	Product data sheet	-	-



## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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